

# Juhyeon Lee

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## Research Fields

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- **Bioelectronics for neuroscience, healthcare, and human-machine interface**
  - ▶ Soft implantable electronics
  - ▶ Physiological sensors
  - ▶ Wireless neural interface

## Education

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| • <b>Integrated M.S/Ph.D. in Electrical Engineering</b><br>KAIST, Daejeon, South Korea<br>Bio-Integrated Electronics and Systems Lab (Advisor: Jae-Woong Jeong) | Mar. 2019 - Present<br>(GPA: 4.08/4.3)    |
| • <b>B.S. in Electrical Engineering</b><br>KAIST, Daejeon, South Korea  | Mar. 2015 - Feb. 2019<br>(GPA: 3.79/4.3)  |
| • <b>High School Diploma</b><br>Hansung Science High School, Seoul, South Korea   | Mar. 2013 - Feb. 2015<br>Early graduation |

## Awards and Honors

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| • <b>Graduate Student Outstanding Paper Award, KAIST</b>               | Nov. 2024             |
| • <b>Government-Sponsored Scholarship, KAIST</b>                       | Mar. 2019 - Present   |
| • <b>BK21 Financial Support for Overseas Long-Term Training, KAIST</b> | Sep. 2022             |
| • <b>Outstanding Teaching Assistant Award, KAIST</b>                   | Apr. 2021             |
| • <b>Cum Laude, KAIST</b>  | Feb. 2019             |
| • <b>National Scholarship for Science and Engineering, KOSAF</b>       | Mar. 2015 - Dec. 2018 |
| • <b>Full Tuition Scholarship, KAIST</b>                               | Mar. 2015 - Dec. 2018 |

## Publications

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[1] H. Kim<sup>†</sup>, **J. Lee<sup>†</sup>**, U. Heo, D. Jayashankar, K.-C. Agno, Y. Kim, C. Y. Kim, Y. Oh, S.-H. Byun, B. Choi, H. Jeong, W.-H. Yeo, Z. Li, S. Park, J. Xiao, J. Kim, J.-W. Jeong (2024). Skin-preparation-free, stretchable microneedle adhesive patches for reliable electrophysiological sensing and exoskeleton robot control. *Science Advances*, 10(3), eadk5260.

- [2] K. E. Parker<sup>†</sup>, **J. Lee**<sup>†</sup>, J. R. Kim<sup>†</sup>, C. Kawakami, C. Y. Kim, R. Qazi, K.-I. Jang, J.-W. Jeong, J. G. McCall (2023). Customizable, wireless, and implantable optogenetic probe design and fabrication via 3D printing. *Nature Protocols*, 18(1), 3-21. **(Featured on the Cover)**
- [3] **J. Lee**<sup>†</sup>, K. E. Parker<sup>†</sup>, C. Kawakami<sup>†</sup>, J. R. Kim<sup>†</sup>, R. Qazi, J. Yea, S. Zhang, C. Y. Kim, J. Bilbily, J. Xiao, K.-I. Jang, J. G. McCall, J.-W. Jeong (2020). Rapidly Customizable, Scalable 3D-Printed Wireless Optogenetic Probes for Versatile Applications in Neuroscience. *Advanced Functional Materials*, 30(46), 2004285. **(Featured on the Back Cover)**
- [4] I. Kang<sup>†</sup>, J. Bilbily<sup>†</sup>, C. Y. Kim, C. Shi, M. K. Madasu, E. Y. Jeong, K. E. Parker, D. A. Kwon, B.-J. Jung, J.-S. Yang, **J. Lee**, N. D. L. Kabbaj, W. Lee, J.-B. Yoon, R. Al-Hasani, J. Xiao, J. G. McCall, J.-W. Jeong (2024). Wireless Modular Implantable Neural Device with One-touch Magnetic Assembly for Versatile Neuromodulation. *Advanced Science*, 2406576.
- [5] S. Oh<sup>†</sup>, S. Lee<sup>†</sup>, S. W. Kim, C. Y. Kim, E. Y. Jeong, **J. Lee**, D. A. Kwon, J.-W. Jeong (2024). Softening Implantable Bioelectronics: Material Designs, Applications, and Future Directions. *Biosensors and Bioelectronics*, 116328.
- [6] G.-H. Lee<sup>†</sup>, H. Kim<sup>†</sup>, **J. Lee**, J.-Y. Bae, M. Kim, C. Yang, S. Park, H. Kang, S.-K. Kang, J. Kang, Z. Bao, J.-W. Jeong, S. Park (2023). Large-area photo-patterning of initially conductive EGaIn particle-assembled film for soft electronics. *Materials Today*, 67, 84-94
- [7] S.-H. Byun<sup>†</sup>, J. Y. Sim<sup>†</sup>, Z. Zhou, **J. Lee**, R. Qazi, M. C. Walicki, K. E. Parker, M. P. Haney, S. H. Choi, A. Shon, G. B. Gereau, J. Bilbily, S. Li, Y. Liu, W.-H. Yeo, J. G. McCall, J. Xiao, J.-W. Jeong (2019). Mechanically transformative electronics, sensors, and implantable devices. *Science advances*, 5(11), eaay0418.

## Conference Presentations

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- [1] **J. Lee**, K. E. Parker, J. G. McCall, J.-W. Jeong (2024). Wireless optoelectronic neural interfaces for simultaneous and spatially-matching optogenetics and electrophysiology. *The 12th World Biomaterials Congress, poster presentation*
- [2] **J. Lee**, K. E. Parker, C. Kawakami, J. R. Kim, R. Qazi, J. Yea, S. Zhang, C. Y. Kim, J. Bilbily, J. Xiao, K.-I. Jang, J. G. McCall, J.-W. Jeong (2021). Customizable and rapidly manufacturable 3D-printed neural probes for wireless optogenetics. *2021 Virtual MRS Spring Meeting & Exhibit, oral presentation*
- [3] H. Kim, **J. Lee**, U. Heo, D. Jayashankar, K.-C. Agno, Y. Kim, C. Y. Kim, Y. Oh, S.-H. Byun, B. Choi, H. Jeong, W.-H. Yeo, Z. Li, S. Park, J. Xiao, J. Kim, J.-W. Jeong (2024). Skin-Preparation-Free, Stretchable Microneedle Adhesive Patches for High-Fidelity Electrophysiological Sensing and Exoskeleton Robot Control. *2024 MRS Spring Meeting & Exhibit, oral presentation*
- [4] H. Kim, **J. Lee**, J.-W. Jeong (2022). Adhesive, Air-permeable, Stretchable Conductive Sensors for Long-term Electrophysiological Signal Monitoring. *The 6th International Conference on Active Materials and Soft Mechatronics*
- [5] S.-H. Byun, J. Y. Sim, Z. Zhou, **J. Lee**, R. Qazi, M. C. Walicki, K. E. Parker, M. P. Haney, S. H. Choi, A. Shon, G. B. Gereau, J. Bilbily, S. Li, Y. Liu, W.-H. Yeo, J. G. McCall, J. Xiao, J.-W. Jeong (2020).

## Experience

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- **Visiting Researcher**, Stanford University, United States
  - ▶ Department of Chemical Engineering, Bao Research Group Sep. 2022 - Feb. 2023
- **Teaching Assistant**, KAIST
  - ▶ Electronics Design Lab (Device, Circuit), MEMS in EE Perspective Sep. 2019 – Dec. 2023
- **Freshman Tutoring Program**, KAIST
  - ▶ General Physics I Mar. 2016 - Jun. 2018
- **Language Exchange Program (German)**, KAIST Fall. 2017
- **Exchange Student**, Karlsruhe Institute of Technology (KIT), Germany
  - ▶ Fakultät für Elektrotechnik und Informationstechnik Mar. - Aug. 2017